

# **System Lens Drivers**

# $\mu$ -step System Lens Driver for Digital Still Cameras

# **BU24036MWV**

### General Description

BU24036MWV is a system Lens Driver that uses  $\mu$ -step driving to make the configuration of the sophisticated, high precision and low noise lens driver system possible. This IC has a built-in driver for both DC moor and voice coil motor and a  $\mu$ -step controller that decreases CPU power. Therefore, multifunctional lens can be applied.

# Features

■ Built-in 6 channels Driver block

1ch-4ch: Voltage control type H-bridge (Adaptable to STM 2systems)

5ch: Voltage / Current control type H-bridge 6ch: Current control type H-bridge

- Built-in 2 channels PI driving circuit
- Built-in 1 channels Waveforming circuit
- Built-in FLL digital servo circuit
- Built-in PLL circuit
- Built-in STM control circuit: Autonomous control (cache / updown mode), Clock IN control

# Applications

■ Digital still cameras

# ●Typical Application Circuit

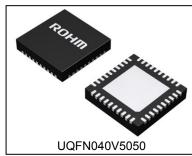
# Key Specifications

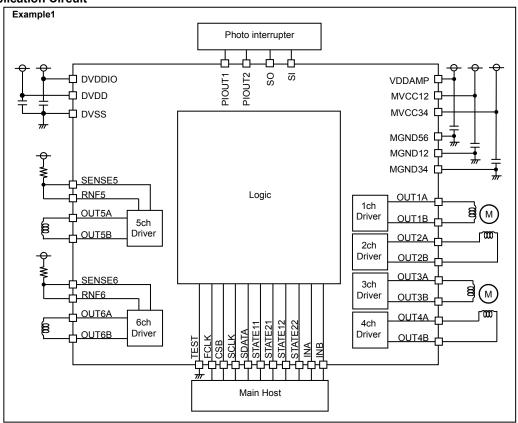
I/O Power Supply Voltage: 1.62V to 3.6V Digital Power Supply Voltage: 2.7V to 3.6V Driver Power Supply Voltage: 2.7V to 5.5V Output Current (1ch-4ch,6ch):  $\pm 500 \text{mA}(\text{Max})$ Output Current (5ch):  $\pm 600$ mA(Max) Input Clock Frequency: 1MHz to 28MHz FET ON Resistance (1ch,2ch):  $2.0\Omega$  (Typ) FET ON Resistance (3ch,4ch):  $1.5\Omega$  (Typ) FET ON Resistance (5ch,6ch): 1.0 Ω (Typ) Operating Temperature Range: -20°C to +85°C

### Package

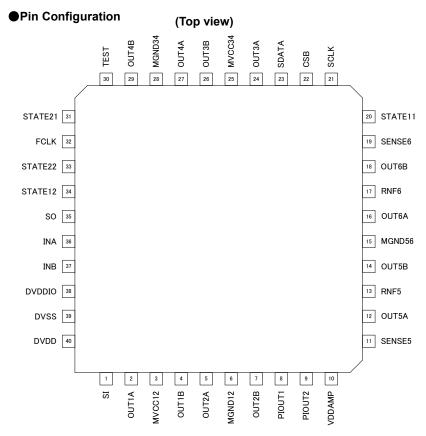
UQFN040V5050

5.00mm x 5.00mm x 1.00mm





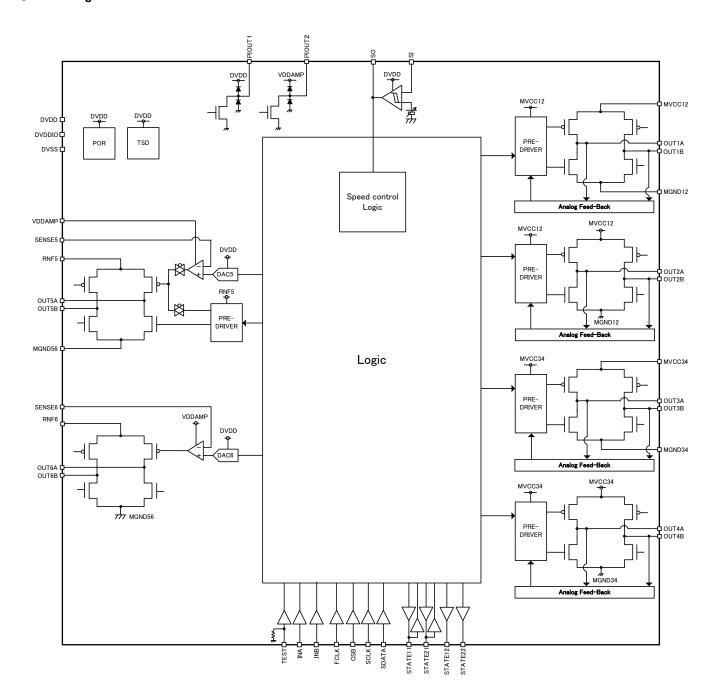
OProduct structure: Silicon monolithic integrated circuit OThis product is not designed for protection against radioactive rays



**●**Pin Description

No.	Pin Name	Power Supply	Function	No.	Pin Name	Power Supply	Function
1	SI	DVDD	Waveforming input	21	SCLK	DVDDIO	SCLK logic input
2	OUT1A	MVCC12	1ch Driver A output	22	CSB	DVDDIO	CSB logic input
3	MVCC12	-	1ch, 2ch Driver power supply	23	SDATA	DVDDIO	SDATA logic input
4	OUT1B	MVCC12	1ch Driver B output	24	OUT3A	MVCC34	3ch Driver A output
5	OUT2A	MVCC12	2ch Driver A output	25	MVCC34	-	3ch, 4ch Driver power supply
6	MGND12	-	1ch, 2ch Driver ground	26	OUT3B	MVCC34	3ch Driver B output
7	OUT2B	MVCC12	2ch Driver B output	27	OUT4A	MVCC34	4ch Driver A output
8	PIOUT1	DVDD	PI driving output 1	28	MGND34	-	3ch, 4ch Driver ground
9	PIOUT2	VDDAMP	PI driving output 2	29	OUT4B	MVCC34	4ch Driver B output
10	VDDAMP	-	5ch, 6ch Power supply of current driver control	30	TEST	DVDDIO	TEST logic input
11	SENSE5	VDDAMP	Negative input for 5ch current driver	31	STATE21	DVDDIO	STATE21 logic input/output
12	OUT5A	RNF5	5ch Driver A output	32	FCLK	DVDDIO	FCLK logic input
13	RNF5	-	5ch Driver power supply	33	STATE22	DVDDIO	STATE22 logic output
14	OUT5B	RNF5	5ch Driver B output	34	STATE12	DVDDIO	STATE12 logic output
15	MGND56	-	5ch,6ch Driver ground	35	SO	DVDDIO	Waveforming output
16	OUT6A	RNF6	6ch Driver A output	36	INA	DVDDIO	INA logic input
17	RNF6	-	6ch Driver power supply	37	INB	DVDDIO	INB logic input
18	OUT6B	RNF6	6ch Driver B output	38	DVDDIO	-	I/O power supply
19	SENSE6	VDDAMP	Negative input for 6ch current driver	39	DVSS		ground
20	STATE11	DVDDIO	STATE11 logic input/output	40	DVDD	-	Digital power supply

# Block Diagram



# Stepping Motor Driver (1ch-4ch Driver)

Built-in stepping motor driver of PWM driving type.

Maximum 2 stepping motors can be driven independently.

Built-in voltage feedback circuit of D-class type.

3ch/4ch drivers can also drive independently for DC motor or voice coil motor.

### (1) Control

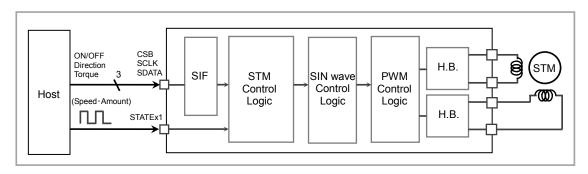
It corresponds to both the Clock IN and the Autonomous control.

# ( i )Clock IN Control

Set the registers for the stepping motor control.

The stepping motor is rotated and synchronized with the input clock in the STATE pin.

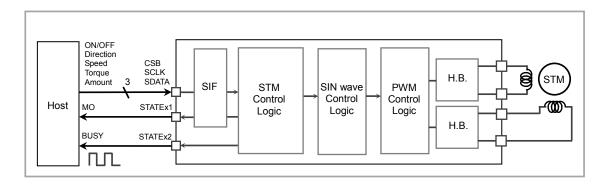
It is possible to select the mode of stepping motor control from  $\mu$ -step, 1-2 phase excitation, 2 phase excitation and the number of edge for electrical angle cycle from 4, 8, 32, 64, 128, 256, 512 or 1024.



### (ii )Autonomous Control

The stepping motor is rotated by setting the registers for the stepping motor control.

It is possible to select the mode of stepping motor control from  $\mu$ -step (1024 portion), 1-2 phase excitation and 2 phase excitation.



# Cache Method

Built-in Cache registers.

Cache registers enable the setting of subsequent process while the motor is in operation. Through these registers, operations are done continuously.

The state of rotation command (ACT), state of Cache registers (BUSY), motor operation position (MO), and state of excitation (MO&EN) are synchronized with the motor rotation and can be selected to be the output of the STATE pin.

# Up Down Method

It is possible to set Up, Constant and Down operation before the motor operates.

The state of rotation command (ACT), Cache register (BUSY), motor position (MO), and excitation (MO&EN) synchronized with the motor rotation are the output of the STATE pin.

# Voltage / Current Driver (5ch Driver)

Built-in voltage driver of PWM driving type / constant current driver.

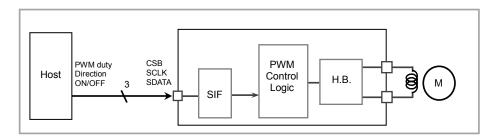
Built-in digital FLL speed control logic for voltage driver.

# (1) Control

# ( i )Register Control

# ■ Voltage Driver (at speed control = OFF)

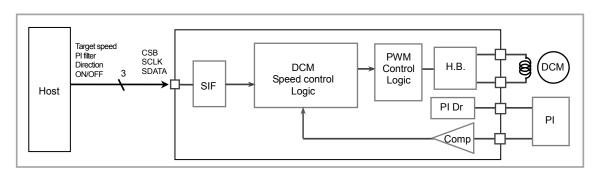
The PWM drive is executed by the PWM duty ratio, the PWM direction and the PWM ON/OFF which are controlled by the register settings.



# ■Voltage Driver (at speed control = ON)

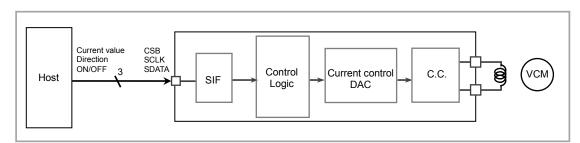
The speed control drive is executed by the target speed value, the direction, the coefficient value of PI filter and the turning ON/OFF which are controlled by the register settings.

The motor speed is adjusted by comparing the target speed with the motor speed detected at the signal of photo-interrupter.



# **■**Current Driver

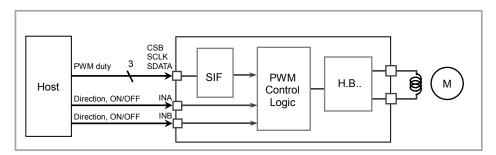
The constant current drive is executed by the output current value, the current direction and the current ON/OFF which are controlled by the register settings.



(ii) External Pin Control

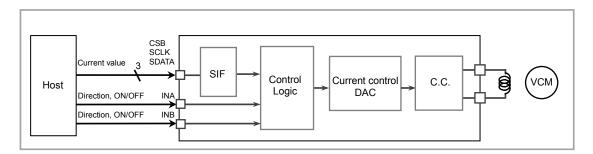
■ Voltage Driver (only at speed control = OFF)

The PWM drive is executed by the PWM duty ratio which is controlled by the register setting. The PWM direction and PWM ON/OFF are controlled by INA/INB pin.



# **■**Current Driver

The constant current drive is executed by the output current value which is controlled by the register setting. Constant current driving direction and turning ON/OFF are controlled by INA/INB pin.



# Current Driver (6ch Driver)

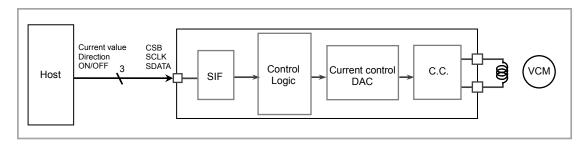
Built-in constant current driver.

The voltage of RNF pin and the external resistor (RRNF) determine the amount of output current. The internal high-precision amplifier (CMOS gate input) is used for the constant current control. If any resistance component exists in the wirings of RNF pin and the external resistor (RRNF), the precision can be reduced. To avoid this, pay utmost attention to the wirings.

# (1) Control

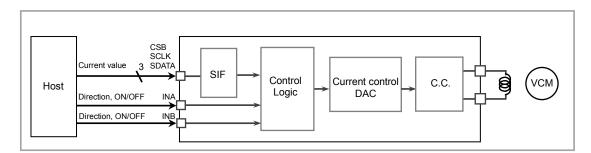
# ( i )Register Control

The constant current drive is executed by the output current value, the current direction and the current ON/OFF which are controlled by the register settings.



# (ii) External Pin Control

The constant current drive is executed by the output current value which is controlled by the register setting. Constant current driving direction and turning ON/OFF are controlled by INA/INB pin.



● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limit	Unit	Remark
Dower Supply Voltage	DVDDIO -0.3 to +4.5		V	
Power Supply Voltage	MVCC	-0.3 to +7.0	V	MVCC12, MVCC34, VDDAMP
Input Voltage	VIN	-0.3 to supply voltage+0.3	V	
		±500	mA	MVCC12, MVCC34, RNF6
Input / Output Current *1	IIN	±600	mA	RNF5
Input / Output Current	IIIN	+50	mA	PIOUT1
		+150	mA	PIOUT2
Storage Temperature Range	TSTG	-55 to +125	°C	
Operating Temperature Range	TOPE	-20 to +85	°C	
Permissible Dissipation *2	PD	2600	mW	

<sup>\*1</sup> Must not exceed PD.

● Recommended Operating Rating (Ta=25°C)

Sommonada Operating (ta 200)							
Parameter	Symbol	Limit	Unit	Remark			
I/O Power Supply	DVDDIO	1.62 to 3.6	V				
Digital Power Supply Voltage	DVDD	2.7 to 3.6	V	DVDD≦MVCC			
Driver Power Supply Voltage	MVCC	2.7 to 5.5	V	MVCC12, MVCC34, RNF5 RNF6, VDDAMP			
Clock Operating Frequency	FCLK	1 to 28	MHz	Reference clock			

<sup>\*2</sup> To use at a temperature higher than Ta=25 °C, derate 26mW per 1 °C (At mounting 74.2mm x 74.2mm x 1.6mm / 4 layer Board)

# **Electrical Characteristics**

Parameter   Symbol   MIN   TYP	MAX	Jnit	Conditions
Quiescence         (DVDDIO)         ISSDO         -         0           (DVDD)         ISSD         -         50           (MVCC)         ISSM         -         0           Operation         (DVDDIO)         IDDDO         -         0.1           (DVDD)         IDDD         -         6 <logic block="">         VIL         DVSS         -           Low-level Input Voltage         VIH         0.7DVDDIO         -           Low-level Input Current         IIL         0         -           High-level Input Current         IIH         0         -</logic>			Conditions
(DVDD)         ISSD         -         50           (MVCC)         ISSM         -         0           Operation         (DVDDIO)         IDDDO         -         0.1           (DVDD)         IDDD         -         6 <logic block="">         VIL         DVSS         -           Low-level Input Voltage         VIH         0.7DVDDIO         -           High-level Input Current         IIL         0         -           High-level Input Current         IIH         0         -</logic>			
(MVCC)     ISSM     -     0       Operation     (DVDDIO)     IDDDO     -     0.1       (DVDD)     IDDD     -     6 <logic block="">       Low-level Input Voltage     VIL     DVSS     -       High-level Input Voltage     VIH     0.7DVDDIO     -       Low-level Input Current     IIL     0     -       High-level Input Current     IIH     0     -</logic>	10 μ	μΑ	CMD_RS=0
Operation (DVDDIO) IDDDO - 0.1  (DVDD) IDDD - 6 <logic block="">  Low-level Input Voltage VIL DVSS - High-level Input Voltage VIH 0.7DVDDIO - Low-level Input Current IIL 0 - High-level Input Current IIH 0</logic>	95 µ	μΑ	
(DVDD) IDDD - 6 <logic block="">  Low-level Input Voltage VIL DVSS - High-level Input Voltage VIH 0.7DVDDIO - Low-level Input Current IIL 0 - High-level Input Current IIH 0</logic>	10 μ	μΑ	
<pre><logic block=""> Low-level Input Voltage</logic></pre>	1 n	mA	CMD_RS=STB=CLK_EN=1 FCLK=24MHz
Low-level Input Voltage  VIL  DVSS  -  High-level Input Voltage  VIH  0.7DVDDIO  -  Low-level Input Current  IIL  0  -  High-level Input Current  IIH  0  -	10 n	mA	CLK_DIV setting : 0h No load
High-level Input Voltage VIH 0.7DVDDIO -  Low-level Input Current IIL 0 -  High-level Input Current IIH 0 -			
Low-level Input Current IIL 0 - High-level Input Current IIH 0 -	0.3DVDDIO	٧	
High-level Input Current IIH 0 -	DVDDIO	٧	
	10 μ	μΑ	VIL=DVSS
Low-level Output Voltage VOL DVSS -	10 μ	μΑ	VIH=DVDDIO
	0.2DVDDIO	٧	IOL=1.0mA
High-level Output Voltage VOH 0.8DVDDIO -	DVDDIO	٧	IOH=1.0mA
<pi circuit="" driving=""></pi>			
Output Voltage PIVO - 0.15	0.5	٧	IIH=30mA
<waveforming circuit=""></waveforming>			
Detective Voltage Error Vth 1.4 1.5	1.6	V	Vth setting : 20h
<voltage 1ch-4ch="" block="" driver=""></voltage>		·	
- 2.0	2.5	Ω	IO=±100mA (the sum of high and low sides, 1ch, 2ch driver)
ON-resistance Ron - 1.5	2.0	Ω	IO=±100mA (the sum of high and low sides, 3ch, 4ch driver)
OFF-leak Current IOZ -10 0	+10 μ	μΑ	Output HiZ setting
Average Voltage Accuracy between different Output Pins Vdiff -5 -	+5	%	Vdiff setting : 2Bh
<voltage 5ch="" block="" current="" driver=""></voltage>			
ON-resistance Ron - 1.0	1.5	Ω	IO=±100mA (the sum of high and low sides)
OFF-leak Current IOZ -10 0	+10 μ	μΑ	Output HiZ setting
Output Current IO 190 200	210 n	mA	At current driver mode DAC setting : 80h RRNF=1Ω
<current 6ch="" block="" driver=""></current>	_		
ON-resistance Ron - 1.0	1.5	Ω	IO=±100mA (the sum of high and low sides)
OFF-leak Current IOZ -10 0	+10 μ	μΑ	Output HiZ setting
Output Current IO 190 200	210 n	mA	DAC setting : 80h RRNF=1Ω

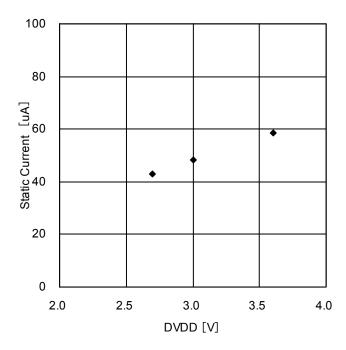


Figure 1. DVDD Static Current Voltage Dependency

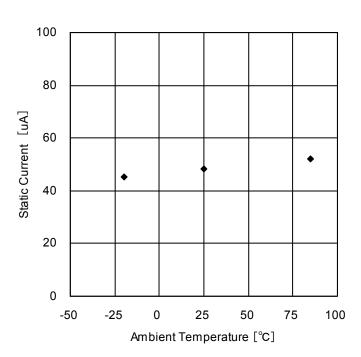


Figure 2. DVDD Static Current Temperature Dependency

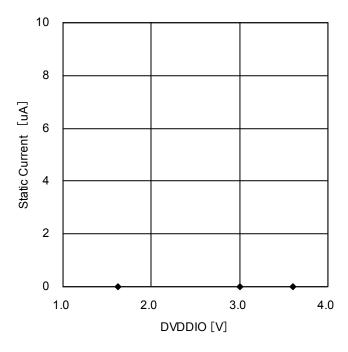


Figure 3. DVDDIO Static Current Voltage Dependency

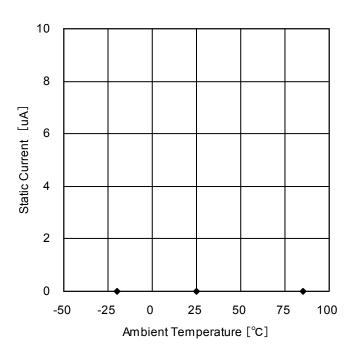


Figure 4. DVDDIO Static Current Temperature Dependency

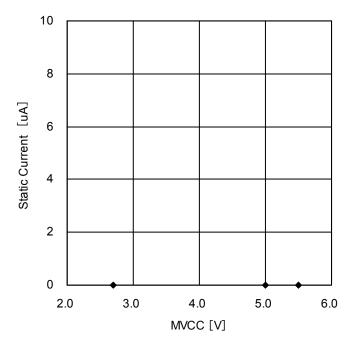


Figure 5. MVCC Static Current Voltage Dependency

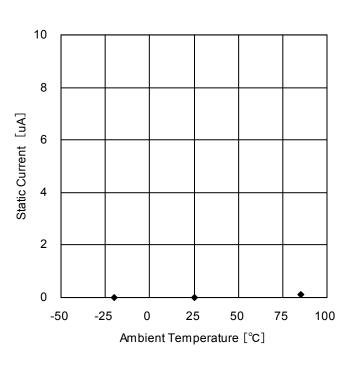


Figure 6. MVCC Static Current Temperature Dependency

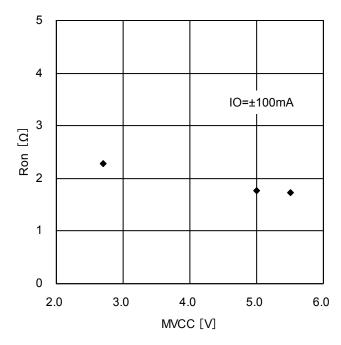


Figure 7. Output ON-Resistance MVCC Dependency (Voltage driver block)

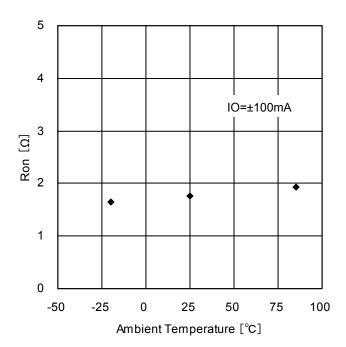


Figure 8. Output ON-Resistance Temperature Dependency (Voltage driver block)

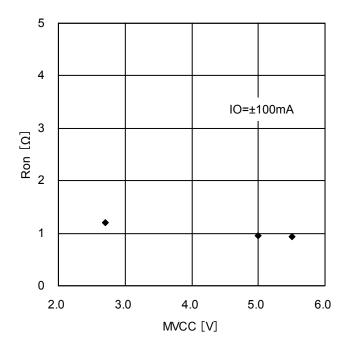


Figure 9. Output ON-Resistance
MVCC Dependency
(Current driver block)

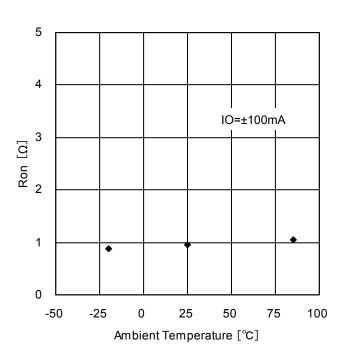


Figure 10. Output ON-Resistance Temperature Dependency (Current driver block)

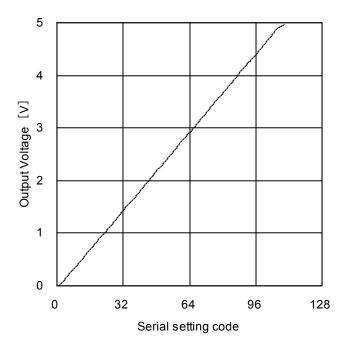


Figure 11. Average Voltage Accuracy between different output pins (Voltage driver block)

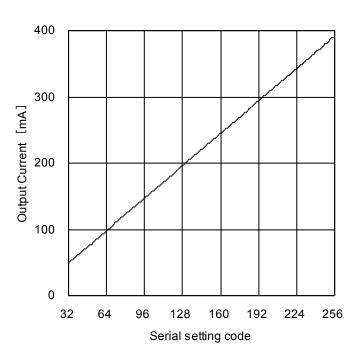


Figure 12. Output Current (Current driver block, RRNF =  $1.0\,\Omega$ , RL =  $5.0\,\Omega$ )

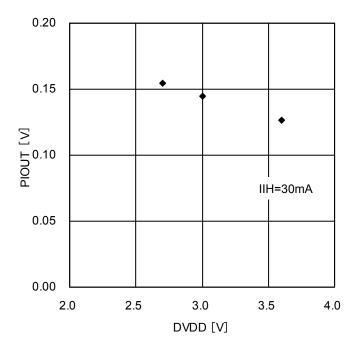


Figure 13. Output Voltage DVDD Dependency (PI driving circuit)

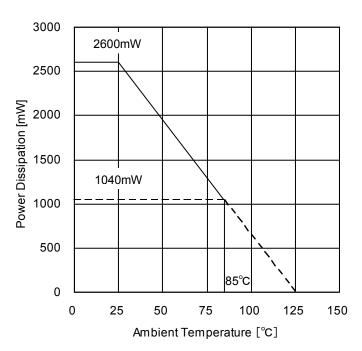
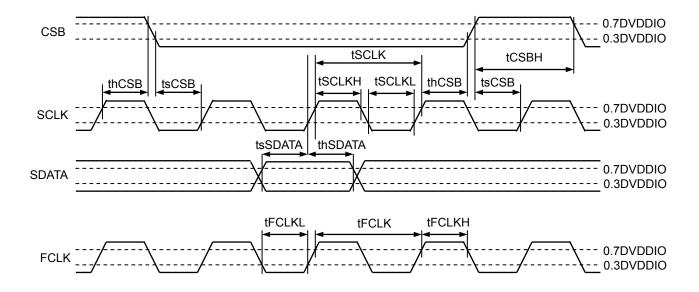


Figure 14. Power Dissipation Curve

# **Timing Chart**

(Unless otherwise specified, Ta=25°C, DVDDIO=DVDD=3.0V)

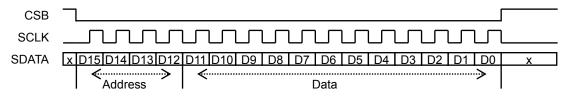
Parameter	Symbol	Specification
SCLK input cycle	tSCLK	More than 100 nsec
SCLK L-level input time	tSCLKL	More than 50 nsec
SCLK H-level input time	tSCLKH	More than 50 nsec
SDATA setup time	tsSDATA	More than 50 nsec
SDATA hold time	thSDATA	More than 50 nsec
CSB H-level input time	tCSBH	More than 380 nsec
CSB setup time	tsCSB	More than 50 nsec
CSB hold time	thCSB	More than 50 nsec
FCLK input cycle	tFCLK	More than 36 nsec
FCLK L-level input time	tFCLKL	More than 18 nsec
FCLK H-level input time	tFCLKH	More than 18 nsec



(note1) FCLK is asynchronous with SCLK. (note2) Duty of FCLK, SCLK are free.

# Serial interface

Control commands are framed by a 16-bit serial input (MSB first) and are sent through the CSB, SCLK, and SDATA pins. The 4 higher-order bits specify addresses, while the remaining 12 bits specify data. Data of every bit is sent through SDATA pin, which is retrieved during the rising edge of SCLK. Data becomes valid when CSB is Low and is registered during the rising edge of CSB.



<Register map>

		ss[3:0			Data[11:0]										
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	A_Mod	de[1:0]	,	A_SEL[2:0] A_different_output_voltage[6:0]						I.		
				0	0	0	0 0 A_Cycle[5:0]					0	0		
				0	0	1	0				A_Cyc	le[13:6]			
0	0	0	1	0	1	0	0	0	0 0 0 A_Sta				A_Start_	POS[3:0]	
	ŭ	ŭ	·	0	1	1	0	A_BEXC	0	0	A_BSL	A_AEXC	0	0	A_ASL
				1	1	1	0	0	0	A_PC	S[1:0]	0	A_UPDW _Stop	A_PS	A_Stop
0	0	1	0	A_EN	A_RT				A_Puls	e[9:0] / A_	UPDW_Cy	cle[9:0]			
0	1	0	0	B_Mod	de[1:0]	I	B_SEL[2:0	]			B_differen	t_output_v	oltage[6:0]		
				0	0	0	0			B_Cyc	de[5:0]			0	0
				0	0	1	0				B_Cyc	le[13:6]			
				0	1	0	0	0	0	0	0		B_Start_	POS[3:0]	
				0	1	1	0	B_BEXC	0	0	B_BSL	B_AEXC	0	0	B_ASL
0	1	0	1	1	0	0	0	0	0	3_CH0	OP[1:0]	0	0	4_CHC	OP[1:0]
				1	0	1		State_CTL[1:0] 3_PWM_Duty[6:0]							
				1	1	0	4_State_	CTL[1:0]		Т	4_P	WM_Duty[			1
				1	1	1	0	0	0 B_POS[1:0] 0 B			B_UPDW _Stop	B_PS	B_Stop	
0	1	1	0	B_EN	B_RT				B_Puls	e[9:0] / B_	UPDW_Cy	cle[9:0]			
1	0	1	1	0	0	0	0	B_ANSEL	A_ANSEL	Edge	0	0	0	B_CTL	A_CTL
	Ů		Ċ	0	0	1	0	0	0	0	0	0	0	EXT_C	TL[1:0]
1	1	0	0	0	0	Choppi		CacheM	0		CLK_EN		CLK_D		I
				0	0	0	0	0	0	0	0	0	0	PI_CTL2	PI_CTL1
				0	0	1	0	DET_SEL	0	SPEI	N[1:0]	0	0	0	0
1	1	0	1	0	1	1	0				TARS	P[7:0]			
				0	1	1	1	0		PSP[2:0]		0		ISP[2:0]	
				1	0	0	0	SPC_ Limit_Out	ut 0 0 0 SPC_Limit[3:0]						
				0	0	0	0				5_IOL	JT[7:0]			
				0	0	1	0	0	5_PWM_Duty[6:0]						
				0	1	0	0	0	0	5_CH0	DP[1:0]	0	0	5_State_	CTL[1:0]
1	1	1	0	0	1	1	0	0	0	0	0	0	6_8	State_CTL[	2:0]
	'	1	J	1	0	0	0				6_10L	JT[7:0]			
				1	0	1	0	0	0			Waveform			
				1	0	1	1	0	0		T	Waveform	_Vthl[5:0]		
				1	1	0	0	0	0	0	STB	0	0	STM_RS	CMD_RS
	and those above Setting prohibited														

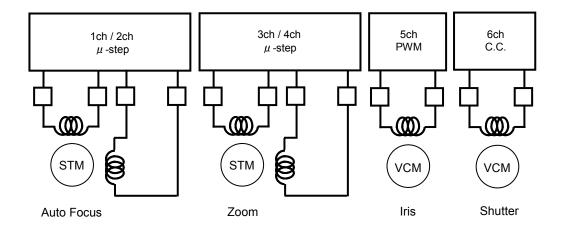
<sup>(</sup>Note 1) The notations A and B in the register map correspond to Ach and Bch respectively. Ach is defined as 1ch and 2ch driver, Bch as 3ch and 4ch driver.

<sup>(</sup>Note 2) After reset (Power ON reset), the initial condition is saved in all registers.

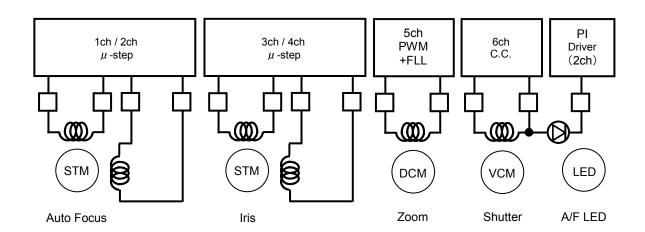
<sup>(</sup>Note 3) For Mode, different output voltage, Cycle, EN, and RT registers, data that are written before the access to the Pulse register becomes valid and determines the rising edge of CSB after the access to the Pulse register.

<sup>(</sup>The Mode, different output voltage, Cycle, EN, RT, and Pulse registers contain Cache registers. Any registers other than those do not contain Cache registers.)

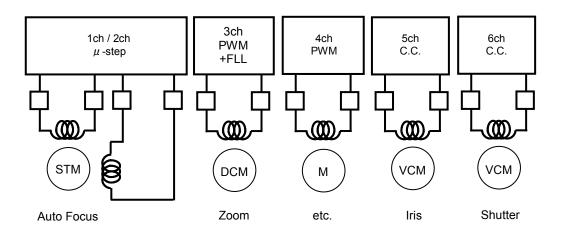
# Application Example



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# ●I/O Equivalence Circuit

O Equivalence Circuit								
Pin	Equivalent Circuit Diagram	Pin	Equivalent Circuit Diagram					
FCLK CSB SCLK SDATA INA INB	DVDDIO DVDDIO	SI	DVDD P					
STATE11 STATE21	DVDDIO DVDDIO DVDDIO	STATE12 STATE22 SO	DVDDIO DVDDIO					
PIOUT1	DVDD P	PIOUT2	VDDAMP P					
OUT1A OUT1B OUT2A OUT2B	MVCC12	OUT3A OUT3B OUT4A OUT4B	MVCC34					
OUT5A OUT5B	RNF5	OUT6A OUT6B	RNF6					

# ●I/O Equivalence Circuit

Pin	Equivalent Circuit Diagram	Pin	Equivalent Circuit Diagram
SENSE5	VDDAMP	SENSE6	VDDAMP P
TEST (note1)	DVDDIO DVDDIO		

(note1) Short TEST pin to DVSS.

# Operational Notes

### 1) Absolute maximum ratings

If applied voltage, operating temperature range, or other absolute maximum ratings are exceeded, the LSI may be damaged. Do not apply voltages or temperatures that exceed the absolute maximum ratings. If you expect that any voltage or temperature could be exceeding the absolute maximum ratings, take physical safety measures such as fuses to prevent any conditions exceeding the absolute maximum ratings from being applied to the LSI.

# 2) GND potential

The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

### 3) Thermal design

Use a thermal design that allows for a sufficient margin by taking into account the permissible power dissipation (PD) in actual operating conditions.

# 4) Short circuit between pins and malfunctions

Ensure that when mounting the IC on the PCB the direction and position are correct. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

# 5) Operation in strong magnetic field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

### 6) Power ON sequence

Set DVDD after the setting of DVDDIO or set it simultaneously. There is no restriction on the setting of MVCC. To turn ON the DVDD, be sure to reset at CMD\_RS register.

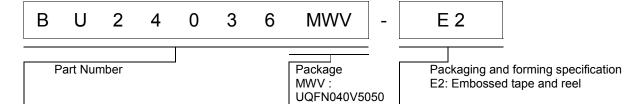
### Thermal shutdown

The IC incorporates a built-in thermal shutdown circuit, which is designed to turn off the IC when the internal temperature of the IC reaches a specified value. It is not designed to protect the IC from damage or guarantee its operation. Do not continue to operate the IC after this function is activated. Do not use the IC in conditions where this function will always be activated.

# 8) PI drive circuit

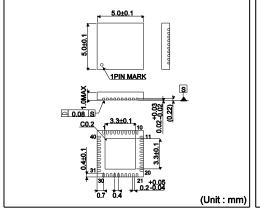
The output voltage of PIOUT1 should not exceed the voltage of the power supply voltage DVDD. The output voltage of PIOUT2 should not exceed the voltage of the power supply voltage VDDAMP.

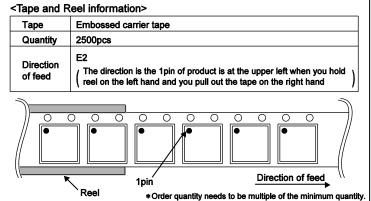
# Ordering Information



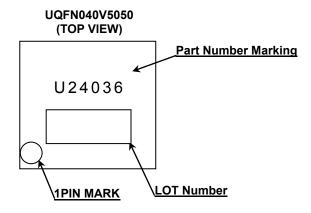
# ●Physical Dimension Tape and Reel Information

# UQFN040V5050





# Marking Diagram



# Revision History

Date	Revision	Changes
10.Oct.2012	001	New Release
2.May.2013	002	Update some English words, sentences, descriptions, grammar and formatting.
20.May.2016	003	Correct Pin Description.

# **Notice**

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1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA	
CLASSⅢ	CL ACCIII	CLASS II b	CLASSIII	
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

# Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

# **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

# **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

# **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

# **Precaution for Foreign Exchange and Foreign Trade act**

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